JJMICROELECTRONICS

100V, 51A,7.8mΩ N-channel Power SGT MOSFET

JMSH1008PKQ

Features

- Ultra-low ON-resistance, $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested
- 100% ΔVds Tested
- Halogen-free; RoHS-compliant
- AEC-Q101 Qualified

Applications

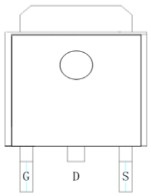
- Load Switch
- PWM Application
- General Automotive Application

Product Summary

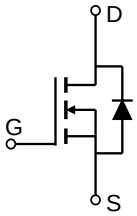
Parameters	Value	Unit
V_{DSS}	100	V
$V_{GS(th)\_Typ}$	3.2	V
I_D(@V_{GS}=10V)	51	A
$R_{DS(ON)\_Typ}$(@V_{GS}=10V)	7.8	mΩ

RoHS

TO-252-3L



Pin Assignment



Schematic Diagram

Ordering Information

Device	Marking	MSL	Form	Package	Reel(pcs)	Per Carton (pcs)
JMSH1008PKQ-13	SH1008PQ	1	Tape&Reel	TO-252-3L	2500	25000

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Symbol	Parameter		Value	Unit
V_{DS}	Drain-to-Source Voltage		100	V
V_{GS}	Gate-to-Source Voltage		±20	V
I_D	Continuous Drain Current	T_C = 25°C	51	A
		T_C = 100°C	36	
I_{DM}	Pulsed Drain Current (1)		Refer to Fig.4	A
E_{AS}	Single Pulsed Avalanche Energy (2)		265	mJ
P_D	Power Dissipation	T_C = 25°C	60	W
		T_C = 100°C	30	
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 175	°C

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient(3)	44	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	2.5	

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	I_D = 250μA, V_{GS} = 0V	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 80V, V_{GS} = 0V	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250μA	2.2	3.2	4.2	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance(4)	V_{GS} = 10V, I_D = 20A	-	7.8	10.1	mΩ
Dynamic Characteristics						
R_g	Gate Resistance	f = 1MHz	-	1.4	-	Ω
C_{iss}	Input Capacitance	V_{GS} = 0V, V_{DS} = 50V, f = 1MHz	1709	2393	3230	pF
C_{oss}	Output Capacitance		305	426	576	pF
C_{rss}	Reverse Transfer Capacitance		16	22	29	pF
Q_g	Total Gate Charge	V_{GS} = 0 to 10V V_{DS} = 50V, I_D = 20A	28	39	53	nC
Q_{gs}	Gate Source Charge		9	13	17	nC
Q_{gd}	Gate Drain("Miller") Charge		-	10	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime	V_{GS} = 10V, V_{DD} = 50V I_D= 20A, R_{GEN} = 3Ω	-	14	-	ns
t_r	Turn-On Rise Time		-	22	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	27	-	ns
t_f	Turn-Off Fall Time		-	10	-	ns
Body Diode Characteristics						
I_S	Maximum Continuous Body Diode Forward Current		-	-	51	A
I_{SM}	Maximum Pulsed Body Diode Forward Current		-	-	206	A
V_{SD}	Body Diode Forward Voltage	V_{GS} = 0V, I_S = 20A	-		1.2	V
trr	Body Diode Reverse Recovery Time	I_F = 20A, di/dt = 100A/us	42	59	79	ns
Qrr	Body Diode Reverse Recovery Charge		-	126	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting T_J=25C, V_{DD}=50V, V_{GS}=10V, R_G=25ohm, L=3mH, I_{AS}=13.3A, V_{DD}=0V during time in avalanche.
3. $R_{\theta JA}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB.
4. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Typical Performance Characteristics

Figure 1: Power De-rating

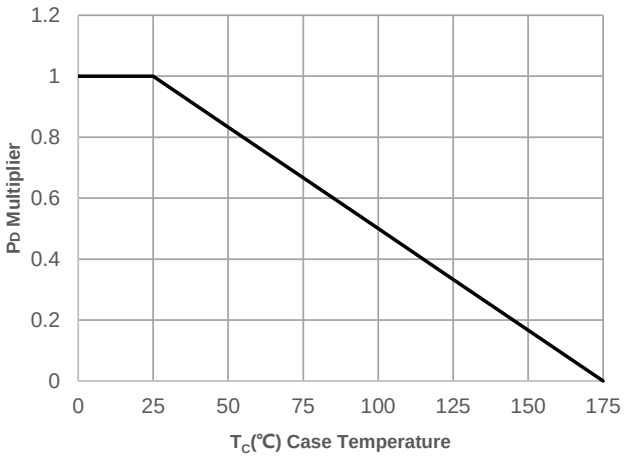


Figure 2: Current De-rating

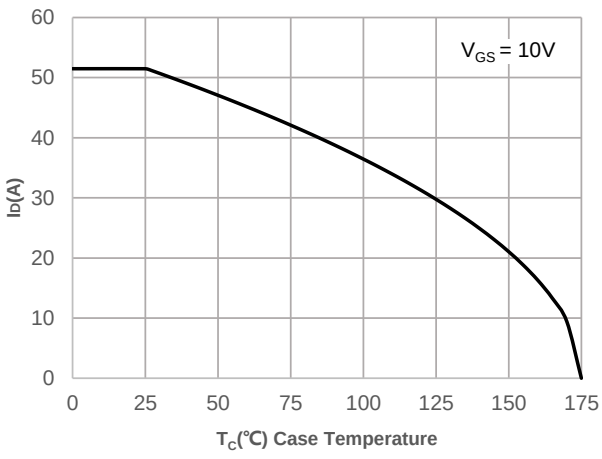


Figure 3: Normalized Maximum Transient Thermal Impedance

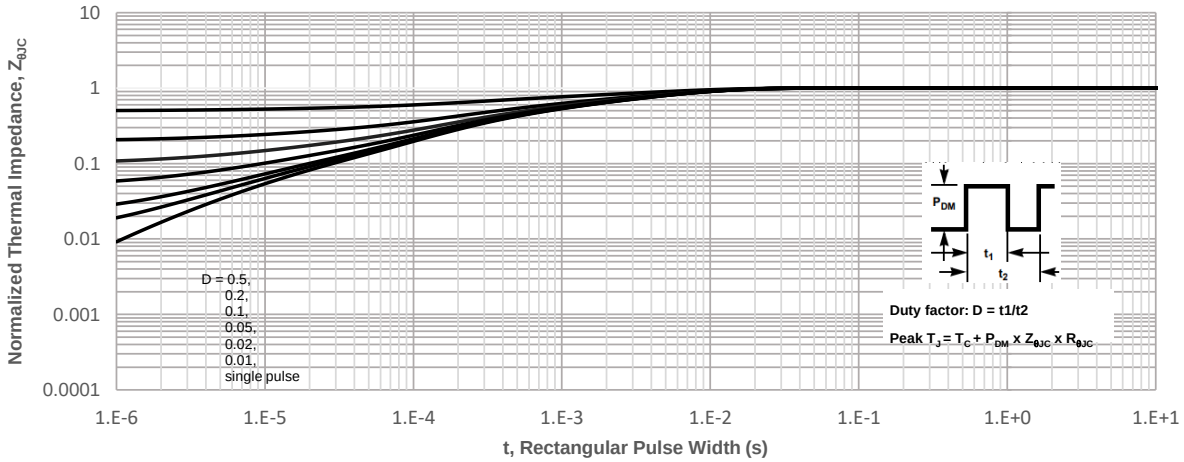
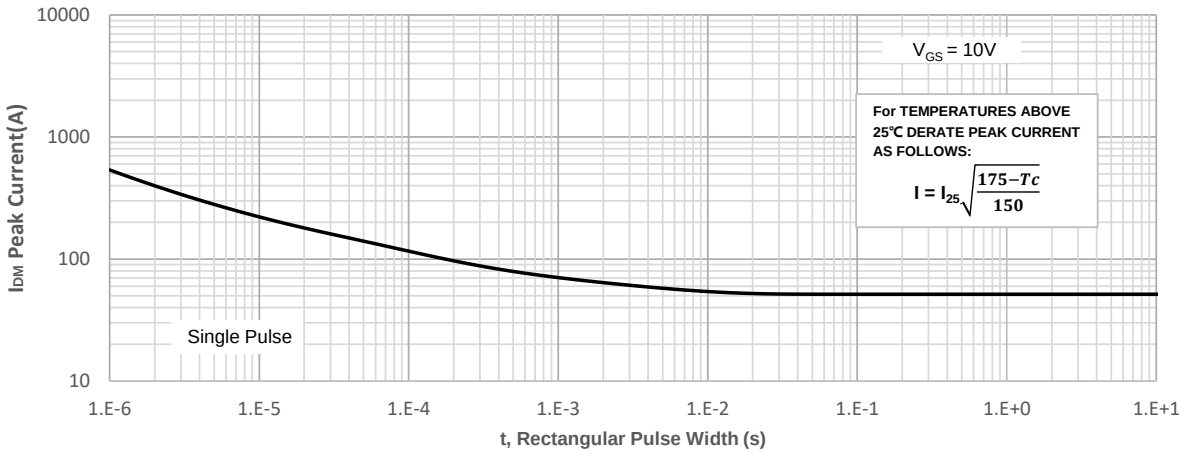


Figure 4: Peak Current Capacity



Typical Performance Characteristics

Figure 5: Output Characteristics

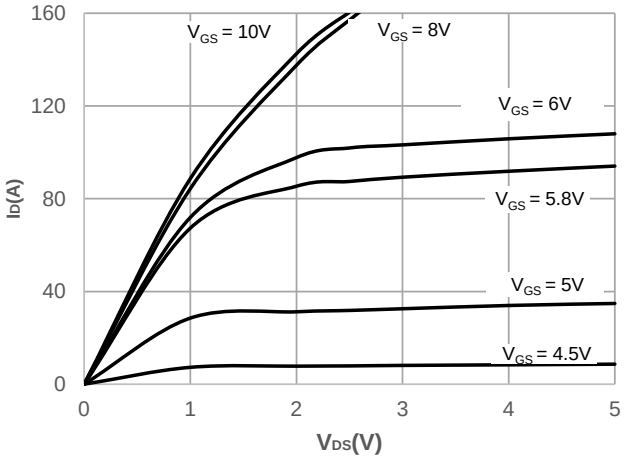


Figure 6: Typical Transfer Characteristics

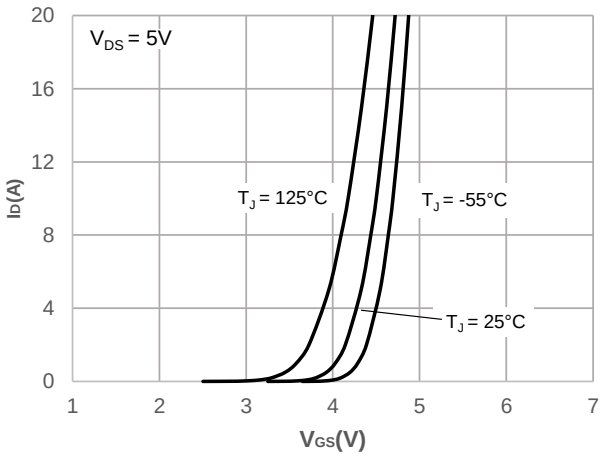


Figure 7: On-resistance vs. Drain Current

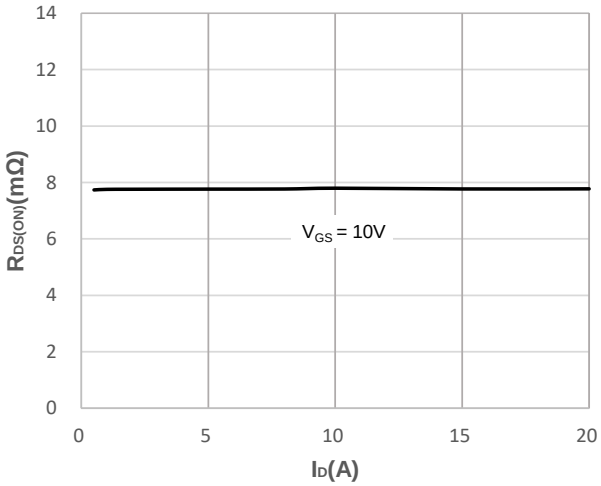


Figure 8: Body Diode Characteristics

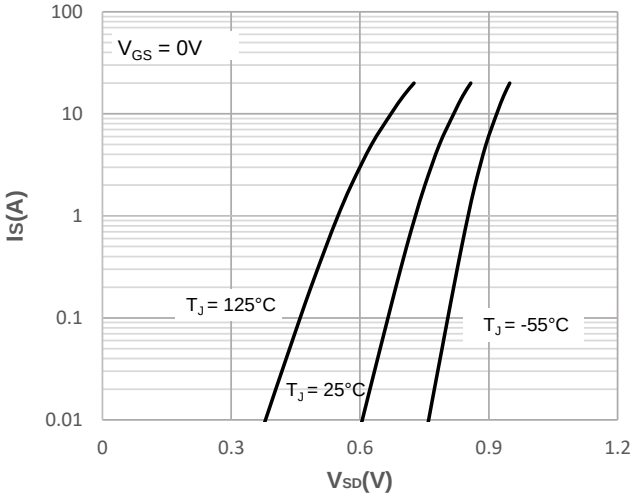


Figure 9: Gate Charge Characteristics

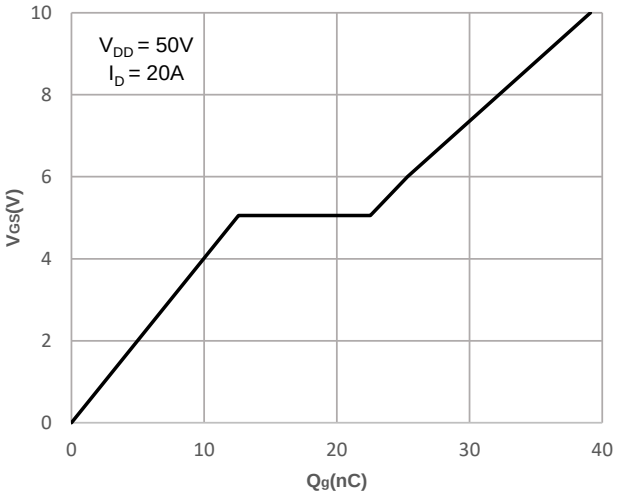
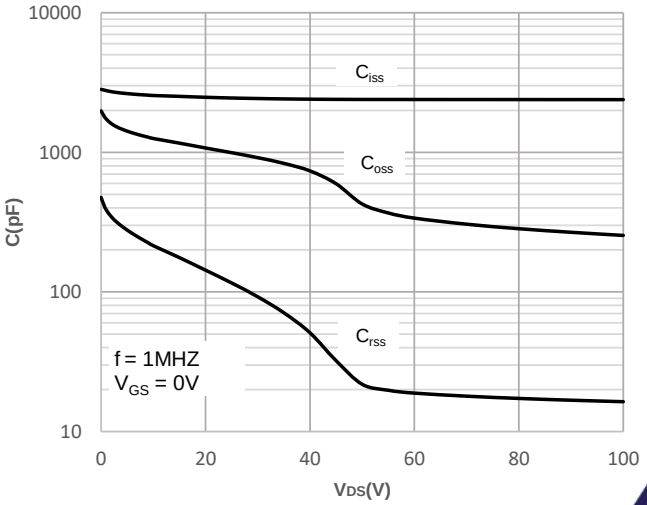


Figure 10: Capacitance Characteristics



Typical Performance Characteristics

Figure 11: Normalized Breakdown voltage vs. Junction Temperature

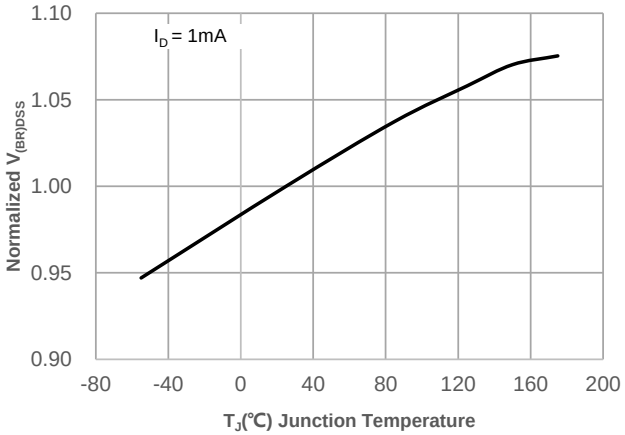


Figure 12: Normalized on Resistance vs. Junction Temperature

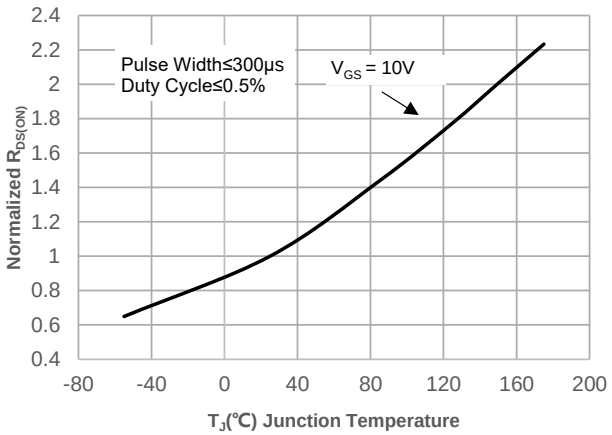


Figure 13: Normalized Threshold Voltage vs. Junction Temperature

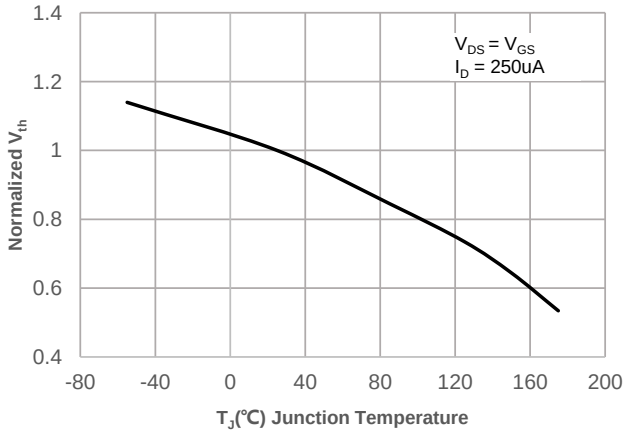


Figure 14: $R_{DS(ON)}$ vs. V_{GS}

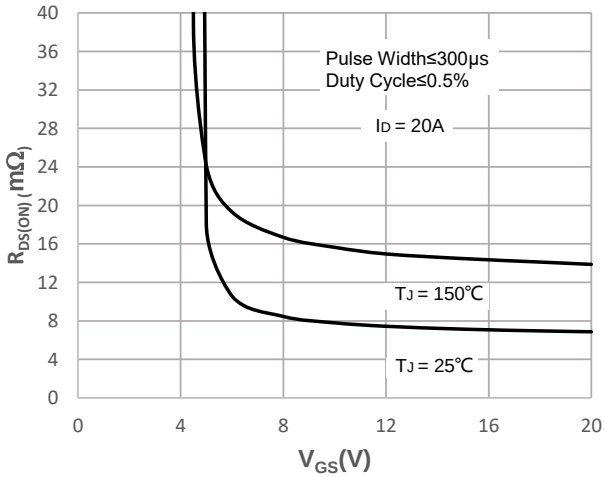
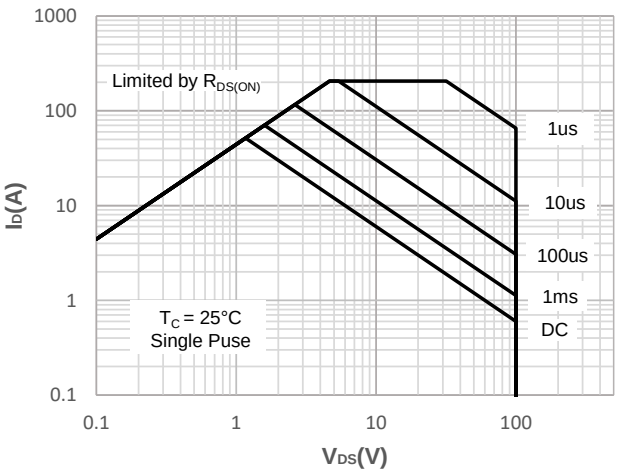


Figure 15: Maximum Safe Operating Area



Test Circuit

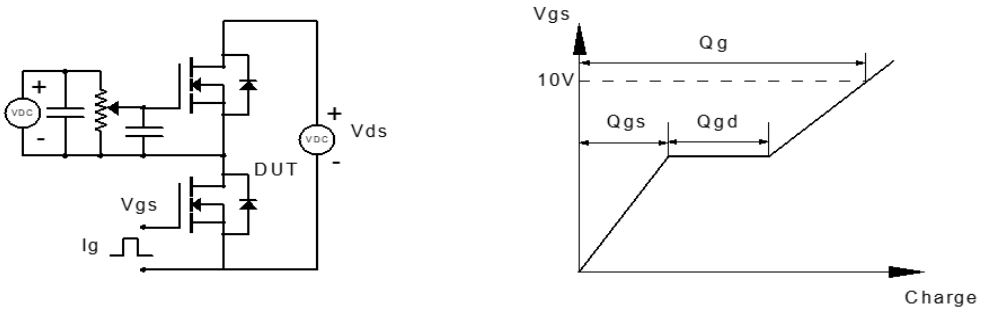


Figure 1: Gate Charge Test Circuit & Waveform

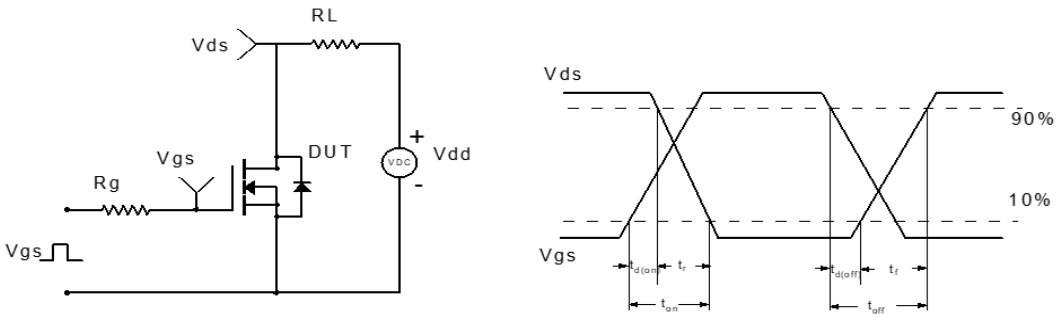


Figure 2: Resistive Switching Test Circuit & Waveform

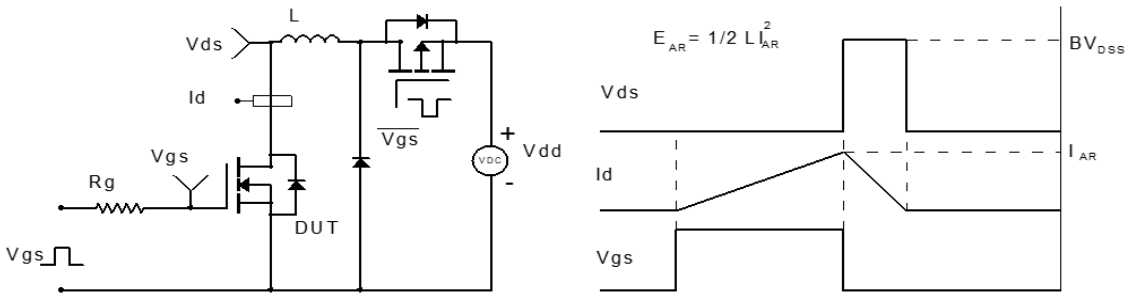


Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

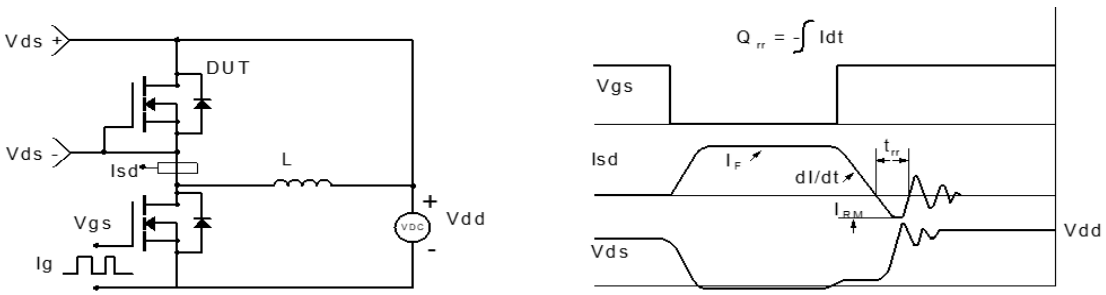
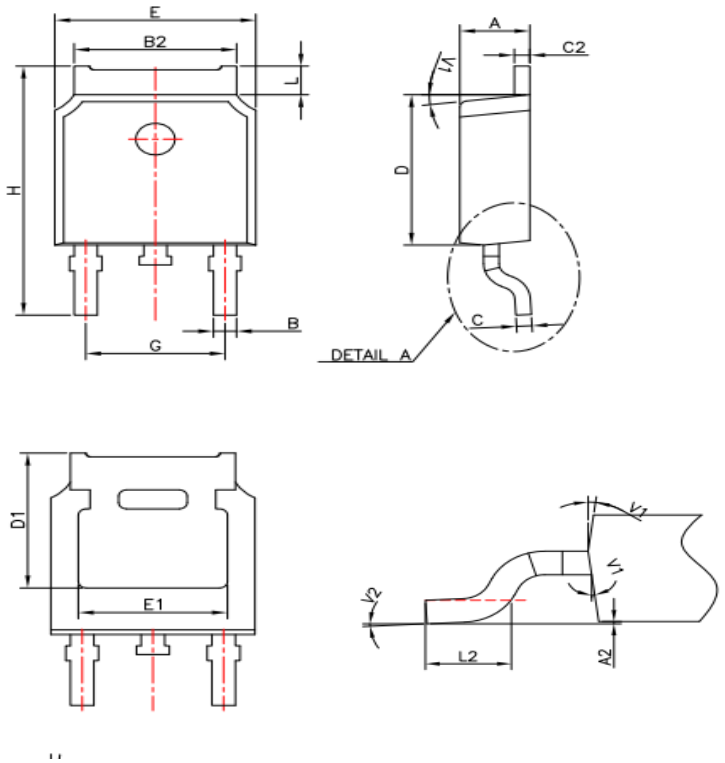


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-3L)



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10	2.30	2.50	0.083	0.091	0.098
A2	0	---	0.15	0	---	0.006
B	0.66	0.76	0.86	0.026	0.030	0.034
B2	5.18	5.33	5.48	0.202	0.210	0.216
C	0.40	0.508	0.60	0.016	0.020	0.024
C2	0.44	0.508	0.58	0.017	0.020	0.023
D	5.90	6.10	6.30	0.232	0.240	0.248
D1		5.30REF			0.209REF	
E	6.40	6.60	6.80	0.252	0.260	0.268
E1		4.826 REF			0.19 REF	
G	4.47	4.57	4.67	0.176	0.180	0.184
H	9.50	10.10	10.70	0.374	0.398	0.421
L	0.95	1.16	1.30	0.037	0.046	0.051
L2	1.35	1.50	1.65	0.053	0.059	0.065
V1	---	7°	---	---	7°	---
V2	0°	---	6°	0°	---	6°